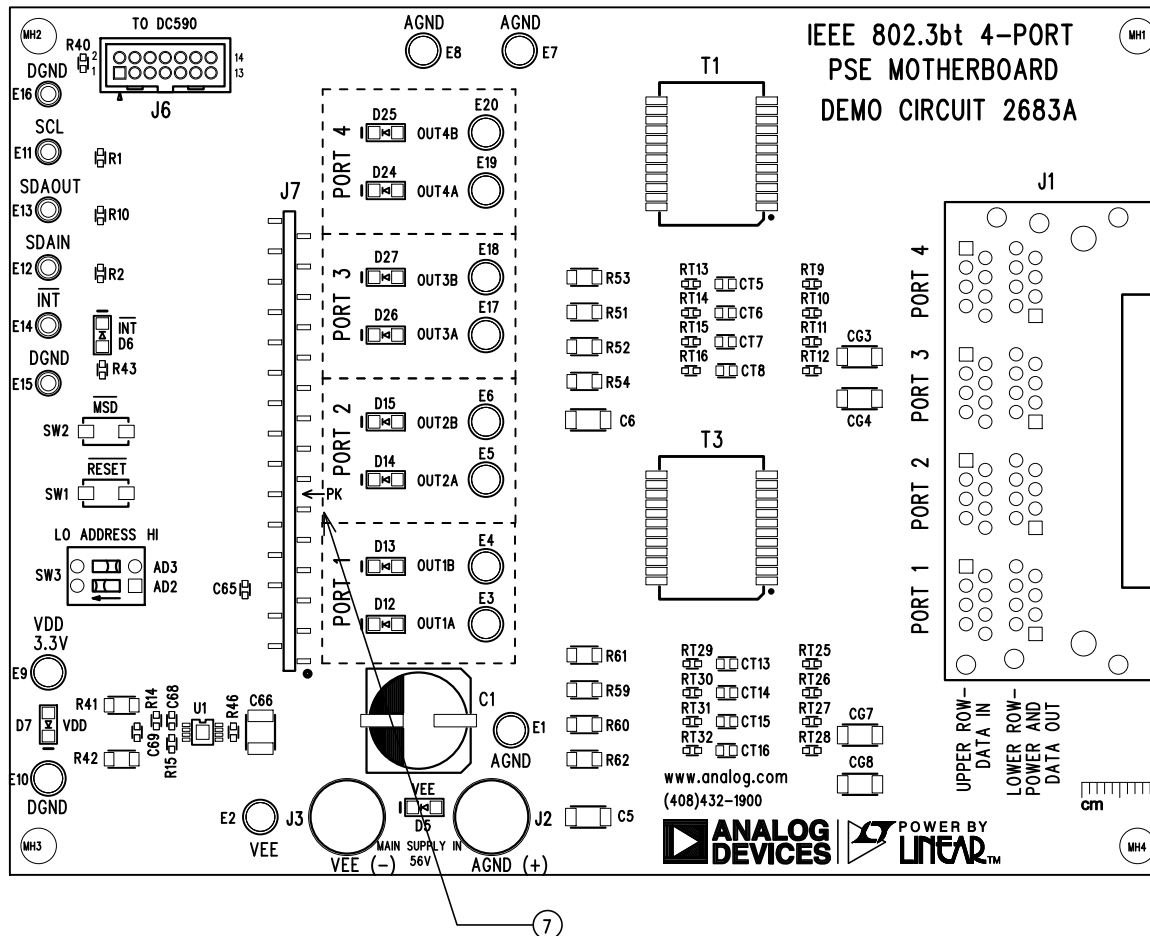
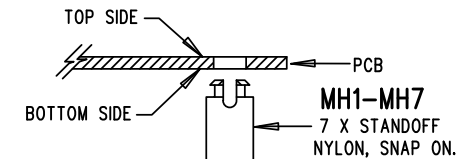


REVISION HISTORY				
ECO	REV	DESCRIPTION	APP. ENG.	DATE
-	1	PRODUCTION	DILIAN R.	03-06-18



NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.
7. INSTALL PK PIN ON J7 PIN 12 AS SHOWN ON DRAWING: ASSY-J7.PDF
8. INSTALL 7 STANDOFFS AS SHOWN BELOW:



APPROVALS		ANALOG DEVICES POWER BY LINEAR™		1630 MCCARTHY BLVD. MILPITAS, CA 95035 TEL: (408)432-1900
PCB DES.	KIM T.	www.analog.com	www.linear.com	
APP ENG.	DILIAN R.	TITLE: TOP ASSEMBLY DRAWING		
		IEEE 802.3bt 4-PORT PSE MOTHERBOARD		
		SIZE N/A	IC NO. DEMO CIRCUIT 2683A	REV. 1
SCALE = NONE		FILENAME: DC2683A-1.PCB		SHT 1 OF 2